Abstract

Chip module (20) with a chip carrier (21) and at least one chip (22), wherein the chip carrier is designed as a sheet with a carrier layer (23) of plastics material and a conductor path structure (24) with conductor paths (28), and the chip carrier is connected to the chip with interposition of a filling material (37), wherein the conductor paths are connected on their front to attachment faces (32) of the chip and, on their rear side (27), have external bonding regions (26) for forming a flatly distributed attachment face arrangement (34) for the connection of the chip module to an electronic component or a substrate (31), and the conductor paths (28) extend in a plane on the chip bonding side (35) of the carrier layer (23) facing the chip (22), the external bonding regions (26) are formed by recesses in the carrier layer (23) which extend toward the rear side (27) of the conductor paths (28) and the carrier layer (23) extends over the region of the attachment faces (30) of the chip.

(Figure 1)